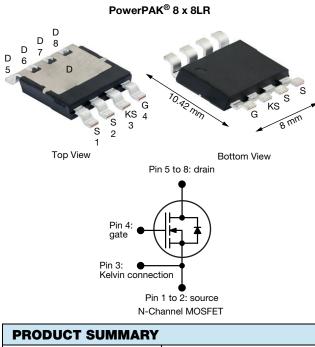
www.vishay.com

Vishay Siliconix

EF Series Power MOSFET With Fast Body Diode



V _{DS} (V) at T _J max.	650			
R _{DS(on)} typ. (Ω) at 25 °C	$V_{GS} = 10 V$	0.075		
Q _g max. (nC)	63			
Q _{gs} (nC)	17			
Q _{gd} (nC)	9			
Configuration	Single			

FEATURES

- 4th generation E series technology
- Low figure of merit (FOM) Ron x Qa
- Low effective capacitance (Co(er))
- Reduced switching and conduction losses
- Avalanche energy rated (UIS)
- Material categorization: for definitions of compliance please see <u>www.vishay.com/doc?99912</u>

APPLICATIONS

- Server and telecom power supplies
- Switch mode power supplies (SMPS)
- Power factor correction power supplies (PFC)
- Lighting
 - High-intensity discharge (HID)
 - Fluorescent ballast lighting
- Industrial
- Welding
- Induction heating
- Motor drives
- Battery chargers
- Solar (PV inverters)

ORDERING INFORMATION			
Package	PowerPAK 8 x 8LR		
Lead (Pb)-free and halogen-free	SiHR085N60EF-T1GE3		

PARAMETER			SYMBOL	LIMIT	UNIT	
Drain-source voltage			V _{DS}	600	v	
Gate-source voltage			V _{GS}	± 30	v	
Continuous drain current (T _J = 150 °C)	V _{GS} at 10 V	T _C = 25 °C	1	50		
	V _{GS} at 10 V	T _C = 100 °C	ID	32	A	
Pulsed drain current ^a			I _{DM}	75		
Linear derating factor				1.47	W/°C	
Single pulse avalanche energy b			E _{AS}	173	mJ	
Maximum power dissipation			PD	184	W	
Operating junction and storage temperature r	ange		T _J , T _{stg}	-55 to +150	°C	
Drain-source voltage slope		T _J = 125 °C	dv/dt 100		V/ns	
Reverse diode dv/dt ^d		av/at	50	V/115		

Notes

a. Repetitive rating; pulse width limited by maximum junction temperature

b. V_{DD} = 120 V, starting T_J = 25 °C, L = 28.2 mH, R_g = 25 $\Omega,\,I_{AS}$ = 3.5 A

c. 1.6 mm from case

d. $I_{SD} \leq I_D$, di/dt = 100 A/µs, starting T_J = 25 °C

S24-1040-Rev. A, 14-Oct-2024

1 For technical questions, contact: <u>hvm@vishay.com</u>





Vishay Siliconix

PARAMETER	SYMBOL	TYP.		MAX.		UNIT		
Maximum junction-to-ambient	R _{thJA}	-		42				
Maximum junction-to-case (drain)	R _{thJC}	- 0.25				- °C/W		
		•						
SPECIFICATIONS ($T_J = 25 \ ^{\circ}C$,	unless otherw	ise noted)						
PARAMETER	SYMBOL		T CONDITI	ONS	MIN.	TYP.	MAX.	UNI
Static							1	
Drain-source breakdown voltage	V _{DS}	V _{GS} =	= 0 V, I _D = 2	50 µA	600	-	-	V
V _{DS} temperature coefficient	$\Delta V_{DS}/T_{J}$	Referenc	e to 25 °C,	I _D = 1 mA	-	0.56	-	V/°C
Gate-source threshold voltage (N)	V _{GS(th)}	V _{DS} =	= V _{GS} , I _D = 2	50 µA	3.0	-	5.0	V
		,	$V_{GS} = \pm 20 V$ $V_{GS} = \pm 30 V$		-	-	± 100	nA
Gate-source leakage	I _{GSS}	,			-	-	± 1	μA
7			= 480 V, V _{GS}		-	-	1	μA
Zero gate voltage drain current	IDSS	$V_{DS} = 480 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 125 \text{ °C}$		-	-	2	mA	
Drain-source on-state resistance	R _{DS(on)}	V _{GS} = 10 V	I _D	= 17 A	-	0.075	0.085	Ω
Forward transconductance ^a	9 _{fs}	V _{DS}	= 10 V, I _D =	17 A	-	16	-	S
Dynamic		•					•	
Input capacitance	C _{iss}	$V_{GS} = 0 V,$ $V_{DS} = 100 V,$ f = 100 KHz $V_{DS} = 0 \text{ V to 400 V}, V_{GS} = 0 \text{ V}$		-	2733	-	pF	
Output capacitance	C _{oss}			-	100	-		
Reverse transfer capacitance	C _{rss}			-	3	-		
Effective output capacitance, energy related ^a	C _{o(er)}			-	107	-		
Effective output capacitance, time related ^b	C _{o(tr)}			-	645	-		
Total gate charge	Qg	V _{GS} = 10 V I _D = 17 A, V _{DS} = 480 V		-	42	63	nC	
Gate-source charge	Q _{gs}			-	17	-		
Gate-drain charge	Q _{gd}				-	9	-	1
Turn-on delay time	t _{d(on)}	V_{DD} = 480 V, I _D = 17 A, V _{GS} = 10 V, R _g = 9.1 Ω		-	32	64		
Rise time	t _r			-	75	113	- ns	
Turn-off delay time	t _{d(off)}			-	48	96		
Fall time	t _f			-	53	80		
Gate input resistance	Rg	f = 1 MHz		0.3	0.7	1.4	Ω	
Drain-Source Body Diode Characterist								
Continuous source-drain diode current	I _S	showing the	MOSFET symbol showing the		-	-	30	
Pulsed diode forward current	I _{SM}	p - n junction diode		-	-	75	A	
Diode forward voltage	V _{SD}	T _J = 25 °C, I _S = 17 A, V _{GS} = 0 V		-	-	1.2	V	
Reverse recovery time	t _{rr}	$T_{J} = 25 \text{ °C}, I_{F} = I_{S} = 17 \text{ A},$ di/dt = 100 A/µs, V _R = 400 V		-	109	218	ns	
Reverse recovery charge	Q _{rr}			-	0.6	1.2	μC	
Reverse recovery current	I _{RRM}			_	11	-	A	

Notes

a. $C_{oss(er)}$ is a fixed capacitance that gives the same energy as C_{oss} while V_{DS} is rising from 0 V to 400 V

b. $C_{oss(tr)}$ is a fixed capacitance that gives the same charging time as C_{oss} while V_{DS} is rising from 0 V to 400 V



Vishay Siliconix

TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

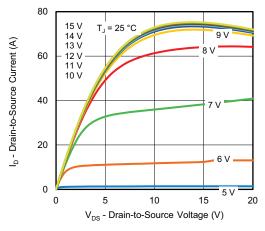


Fig. 1 - Typical Output Characteristics

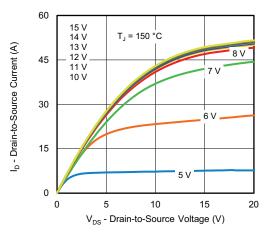


Fig. 2 - Typical Output Characteristics

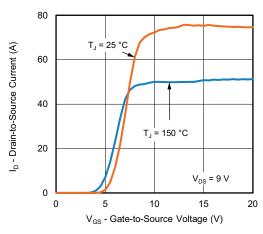


Fig. 3 - Typical Transfer Characteristics

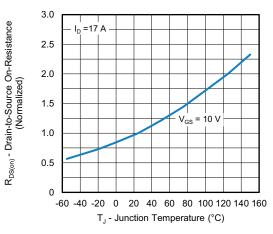


Fig. 4 - Normalized On-Resistance vs. Temperature

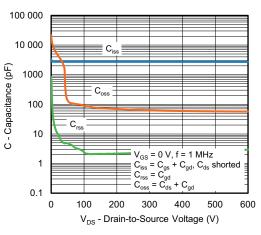
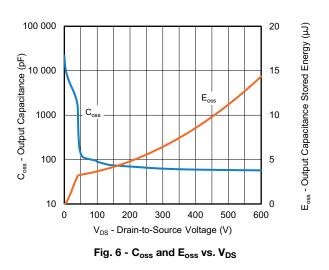


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage



3

Document Number: 92565

For technical questions, contact: <u>hvm@vishay.com</u> THIS DOCUMENT IS SUBJECT TO CHANGE WITHOUT NOTICE. THE PRODUCTS DESCRIBED HEREIN AND THIS DOCUMENT ARE SUBJECT TO SPECIFIC DISCLAIMERS, SET FORTH AT <u>www.vishay.com/doc?91000</u>



Vishay Siliconix

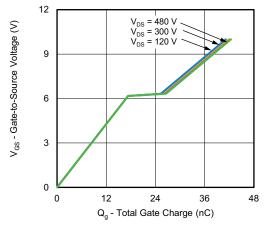


Fig. 7 - Typical Gate Charge vs. Gate-to-Source Voltage

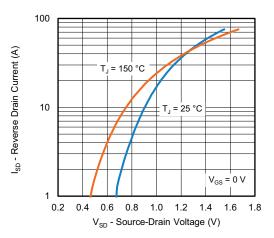


Fig. 8 - Typical Source-Drain Diode Forward Voltage

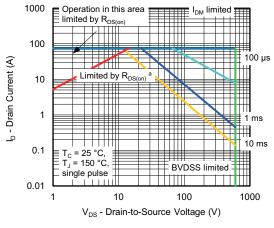


Fig. 9 - Maximum Safe Operating Area

Note

a. V_{GS} > minimum V_{GS} at which $R_{DS(on)}$ is specified

S24-1040-Rev. A, 14-Oct-2024

4

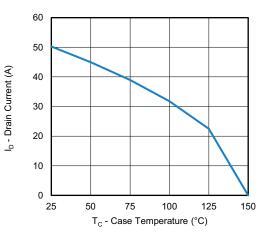


Fig. 10 - Maximum Drain Current vs. Case Temperature

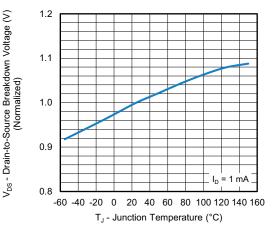


Fig. 11 - Temperature vs. Drain-to-Source Voltage



Vishay Siliconix

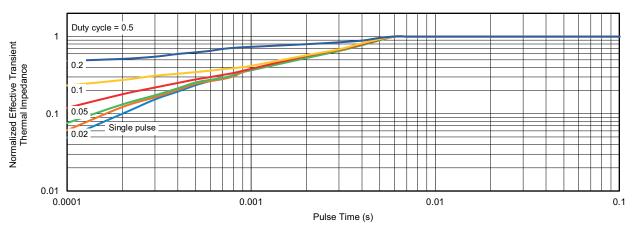


Fig. 12 - Normalized Transient Thermal Impedance, Junction-to-Case

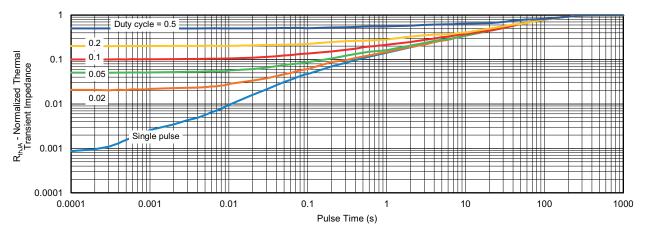


Fig. 13 - Normalized Transient Thermal Impedance, Junction-to-Ambient

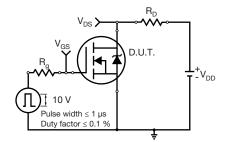


Fig. 14 - Switching Time Test Circuit

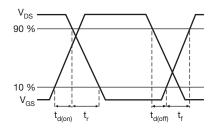


Fig. 15 - Switching Time Waveforms



Vishay Siliconix

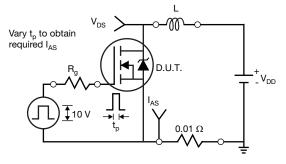


Fig. 16 - Unclamped Inductive Test Circuit

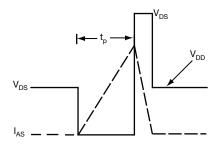


Fig. 17 - Unclamped Inductive Waveforms

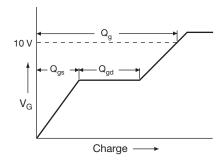


Fig. 18 - Basic Gate Charge Waveform

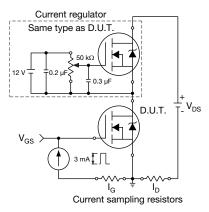
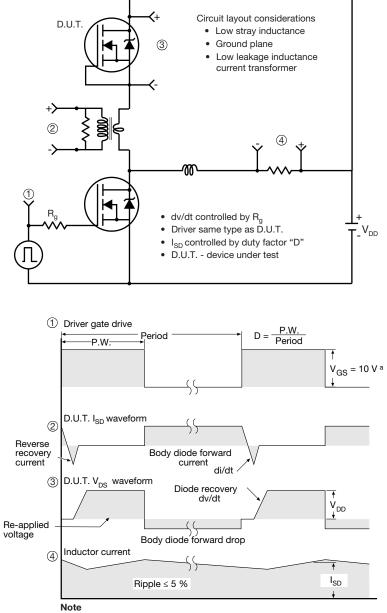


Fig. 19 - Gate Charge Test Circuit





Peak Diode Recovery dv/dt Test Circuit



a. $V_{GS} = 5$ V for logic level devices

Fig. 20 - For N-Channel

Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package / tape drawings, part marking, and reliability data, see www.vishay.com/ppg?92565.



Vishay

Disclaimer

ALL PRODUCT, PRODUCT SPECIFICATIONS AND DATA ARE SUBJECT TO CHANGE WITHOUT NOTICE TO IMPROVE RELIABILITY, FUNCTION OR DESIGN OR OTHERWISE.

Vishay Intertechnology, Inc., its affiliates, agents, and employees, and all persons acting on its or their behalf (collectively, "Vishay"), disclaim any and all liability for any errors, inaccuracies or incompleteness contained in any datasheet or in any other disclosure relating to any product.

Vishay makes no warranty, representation or guarantee regarding the suitability of the products for any particular purpose or the continuing production of any product. To the maximum extent permitted by applicable law, Vishay disclaims (i) any and all liability arising out of the application or use of any product, (ii) any and all liability, including without limitation special, consequential or incidental damages, and (iii) any and all implied warranties, including warranties of fitness for particular purpose, non-infringement and merchantability.

Statements regarding the suitability of products for certain types of applications are based on Vishay's knowledge of typical requirements that are often placed on Vishay products in generic applications. Such statements are not binding statements about the suitability of products for a particular application. It is the customer's responsibility to validate that a particular product with the properties described in the product specification is suitable for use in a particular application. Parameters provided in datasheets and / or specifications may vary in different applications and performance may vary over time. All operating parameters, including typical parameters, must be validated for each customer application by the customer's technical experts. Product specifications do not expand or otherwise modify Vishay's terms and conditions of purchase, including but not limited to the warranty expressed therein.

Hyperlinks included in this datasheet may direct users to third-party websites. These links are provided as a convenience and for informational purposes only. Inclusion of these hyperlinks does not constitute an endorsement or an approval by Vishay of any of the products, services or opinions of the corporation, organization or individual associated with the third-party website. Vishay disclaims any and all liability and bears no responsibility for the accuracy, legality or content of the third-party website or for that of subsequent links.

Vishay products are not designed for use in life-saving or life-sustaining applications or any application in which the failure of the Vishay product could result in personal injury or death unless specifically qualified in writing by Vishay. Customers using or selling Vishay products not expressly indicated for use in such applications do so at their own risk. Please contact authorized Vishay personnel to obtain written terms and conditions regarding products designed for such applications.

No license, express or implied, by estoppel or otherwise, to any intellectual property rights is granted by this document or by any conduct of Vishay. Product names and markings noted herein may be trademarks of their respective owners.

© 2025 VISHAY INTERTECHNOLOGY, INC. ALL RIGHTS RESERVED

Revision: 01-Jan-2025

1